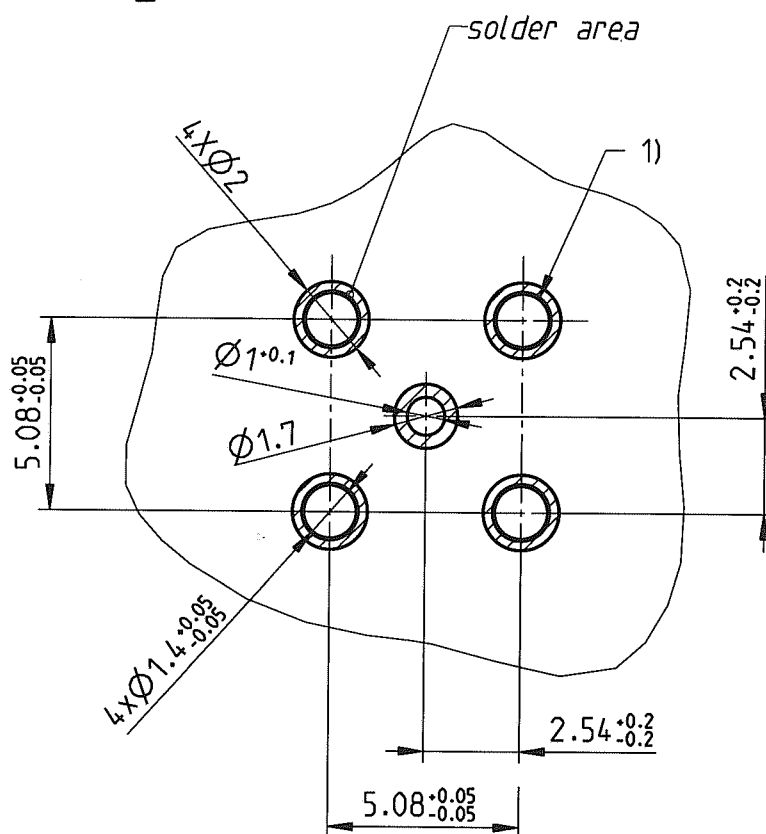


Leiterplatten-Layout
PCB layout
B 273



- 1) 5 Bohrungen durchkontaktieren mit Restringen auf Rueckseite. (Restringbreite 0.25 mm min.)
5 drill holes plated inclusive pads on the backside. (padwidth 0.25 mm min.)

A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector.

Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector.

In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Rosenberger Hochfrequenztechnik 84526 Tittmoning Pro/ENGINEER				general tolerance ISO 2768 m-H RN 006-01 dimensions <0.5 and symmetry				scale: 5:1 weight[g]: surface[mm²]:
				drawn 29.08.2007 check. 20.05.08 appr. 20.05.08	date 29.08.2007 name U. Koebele	title: Leiterplatten-Layout PCB layout		
				dimensioning incl. finish				drawing-no.: MB_273
a00 100 rev.	08-s238 07-m332 change-no	U_Koebele U_Koebele name	19.05.2008 29.08.2007 date	distribu- tion to:	FE X	AZ .	QSM .	RMT .
remarks:								sheet: 1 of: 1